

**GLIDE HEADS AND
METHODS FOR MAKING GLIDE HEADS**

ABSTRACT OF THE DISCLOSURE

An improved glide head has an air bearing surface with a flatness of less than about 1 μ inch. The air bearing surfaces are formed from the very smooth and flat surface of a wafer, preferably prior to slicing the glide heads from the wafer. Thus, a wafer is formed having a flat surface with a plurality of air bearing surface contoured onto the surface. To form a glide head, a transducer can be mounted on the air bearing surface or the surface opposite the air bearing surface, preferably at the wafer level before slicing.

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